

APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C to 85 °C <sup>(1)</sup>	STORAGE TEMPERATURE RANGE	-10 °C to 60 °C <sup>(2)</sup>	
	VOLTAGE	50 V AC	STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 85 % MAX (NOT DEWED)	
	CURRENT	0.5 A	OPERATING HUMIDITY RANGE		
SPECIFICATIONS					
ITEM		TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	×	×
MARKING		CONFIRMED VISUALLY.		×	×
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA (DC OR 1000 Hz)	70 mΩ MAX .	×	—
INSULATION RESISTANCE		100 V DC.	100 MΩ MIN.	×	—
VOLTAGE PROOF		150 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	×	×
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.	INSERTION FORCE : 14 N MAX. WITHDRAWAL FORCE: 1.8 N MIN.	×	—
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.	1) CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. 2) NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	—
VIBRATION		FREQUENCY 10 TO 55 TO 10 Hz, APPROX 5 min. SINGLE AMPLITUDE: 0.75 mm, 10 CYCLES FOR 3 AXIAL DIRECTIONS.	1) NO ELECTRICAL DISCONTINUITY OF 1 μs. 2) NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	—
SHOCK		490 m/s <sup>2</sup> , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 BOTH AXIAL DIRECTIONS.		×	—
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.	1) CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	×	—
RAPID CHANGE OF TEMPERATURE		TEMPERATURE: -55 → +85 °C TIME : 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2 TO 3 min)	2) INSULATION RESISTANCE: 100 MΩ MIN. 3) NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	—
COLD		EXPOSED AT -55 °C, 96 h	1) CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	×	—
DRY HEAT		EXPOSED AT +85 °C, 96 h	2) NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	—
SULFUR DIOXIDE		EXPOSED AT 25 ± 2 °C, 75 ± 5 %RH, 25 ppm FOR 96 h. (TEST STANDARD: JIS C 60068)	1) NO DEFECT SUCH AS CORROSION WHICH IMPAIRS THE FUNCTION OF CONNECTOR. 2) CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	×	—
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING: PEAK TMP : 260 °C MAX REFLOW TMP: 220 °C MIN FOR 60sec 2) SOLDERING IRONS: 360 °C MAX FOR 5 sec.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	×	—
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240 ± 3 °C FOR IMMERSION DURATION, 3 sec.	A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	×	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△					
REMARKS			APPROVED	HS. OKAWA	16.01.16
(1) INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING.			CHECKED	HT. YAMAGUCHI	16.01.16
(2) "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNPACKED PART BEFORE ASSEMBLY TO PCB.			DESIGNED	MT. ITANO	16.01.16
Unless otherwise specified, refer to IEC-60512.			DRAWN	MT. ITANO	16.01.16
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-349945-20-00
HRS	SPECIFICATION SHEET		PART NO.	FX20-20P-0.5SV15 (20)	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL570-1014-2-20	△ 1/1